

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the Correct Zip code of Assignee on Notice of Recordation - recordation date: 07/21/2008 previously recorded on Reel 021268 Frame 0370. Assignor(s) hereby confirms the Assignment of Assignors' interest in USSN 12142589 to Vertical Circuits, Inc. (Assignee).

**CONVEYING PARTY DATA**

Name	Execution Date
Simon J.S. McElrea	06/26/2008
Terrence Caskey	06/26/2008
Scott McGrath	06/26/2008
DeAnn Eileen Melcher	06/26/2008
Lawrence Douglas Andrews Jr.	06/27/2008
Weiping Pan	06/26/2008
Yong Du	07/11/2008
Scott Jay Crane	07/14/2008
Zongrong Liu	06/30/2008

**RECEIVING PARTY DATA**

<b>Name:</b>	Vertical Circuits, Inc.
<b>Street Address:</b>	10 Victor Square
<b>City:</b>	Scotts Valley
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95066

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12142589

**CORRESPONDENCE DATA**

Fax Number: (650)712-0263  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
 Phone: 6507120340  
 Email: crosemond@hmbay.com  
 Correspondent Name: Bill Kennedy

OP \$40.00 12142589

Address Line 1: 637 Main Street  
Address Line 4: Half Moon Bay, CALIFORNIA 94019

ATTORNEY DOCKET NUMBER: VICX 1026-2

NAME OF SUBMITTER: Bill Kennedy

**Total Attachments: 18**

source=CorrectiveAssignment#page1.tif  
source=CorrectiveAssignment#page2.tif  
source=CorrectiveAssignment#page3.tif  
source=CorrectiveAssignment#page4.tif  
source=CorrectiveAssignment#page5.tif  
source=CorrectiveAssignment#page6.tif  
source=CorrectiveAssignment#page7.tif  
source=CorrectiveAssignment#page8.tif  
source=CorrectiveAssignment#page9.tif  
source=CorrectiveAssignment#page10.tif  
source=CorrectiveAssignment#page11.tif  
source=CorrectiveAssignment#page12.tif  
source=CorrectiveAssignment#page13.tif  
source=CorrectiveAssignment#page14.tif  
source=CorrectiveAssignment#page15.tif  
source=CorrectiveAssignment#page16.tif  
source=CorrectiveAssignment#page17.tif  
source=CorrectiveAssignment#page18.tif

<b>PATENT ASSIGNMENT</b>
--------------------------

Electronic Version v1.1  
 Stylesheet Version v1.1

**07/21/2008**  
**500598552**

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Simon J.S. McElrea	06/26/2008
Terrence Caskey	06/26/2008
Scott McGrath	06/26/2008
DeAnn Eileen Melcher	06/26/2008
Reynaldo Co	06/26/2008
Lawrence Douglas Andrews Jr.	06/27/2008
Weiping Pan	06/26/2008
Grant Villavicencio	06/30/2008
Yong Du	07/11/2008
Scott Jay Crane	07/14/2008
Zongrong Liu	06/30/2008
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Vertical Circuits, Inc.
<b>Street Address:</b>	10 Victor Square
<b>City:</b>	Scotts Valley
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	<del>94019</del> 95066
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	12142589
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(650)712-0263
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	650-712-0340
<b>Email:</b>	bkennedy@hmbay.com
<b>Correspondent Name:</b>	HAYNES BEFFEL & WOLFELD LLP

OP \$40.00 12142589

TO:HAYNES BEFFEL &amp; WOLFELD LL COMPANY:P O BOX 366

Address Line 1:	P O BOX 366
Address Line 4:	HALF MOON BAY, CALIFORNIA 94019
ATTORNEY DOCKET NUMBER:	VCIX 1026-2
NAME OF SUBMITTER:	Carol Rosemond
Total Attachments: 11 source=AssignVCIX1026-2#page1.tif source=AssignVCIX1026-2#page2.tif source=AssignVCIX1026-2#page3.tif source=AssignVCIX1026-2#page4.tif source=AssignVCIX1026-2#page5.tif source=AssignVCIX1026-2#page6.tif source=AssignVCIX1026-2#page7.tif source=AssignVCIX1026-2#page8.tif source=AssignVCIX1026-2#page9.tif source=AssignVCIX1026-2#page10.tif source=AssignVCIX1026-2#page11.tif	

**JOINT TO CORPORATE  
ASSIGNMENT**

WHEREAS, the undersigned,

- |   |  |
|---|--|
| (1) Simon J.S. McElrea<br>621 Acorn Court<br>Scotts Valley, CA 95066        | (2) Terrence Caskey<br>236 John Street<br>Santa Cruz, CA 95606                           |
| (3) Scott McGrath<br>13 Terrace View Court<br>Scotts Valley, CA 95066       | (4) DeAnn Eileen Melcher<br>6006 Guadalupe Mines Road<br>San Jose, CA 95120              |
| (5) Reynaldo Co<br>1753 Glenwood Drive<br>Scotts Valley, CA 95066           | (6) Lawrence Douglas Andrews, Jr.<br>22545 Old Santa Cruz Highway<br>Los Gatos, CA 95033 |
| (7) Weiping Pan<br>726 Los Padres Boulevard<br>Santa Clara, CA 95050        | (8) Grant Villavicencio<br>1753 Glenwood Drive<br>Scotts Valley, CA 95066                |
| (9) Yong Du<br>10190 N. Foothill Boulevard<br>Cupertino, CA 95014           | (10) Scott Jay Crane<br>19388 Oak Ridge Drive<br>Aromas, CA 95004                        |
| (11) Zongrong Liu<br>7375 Rollingdell Drive, Unit 72<br>Cupertino, CA 95014 |  |

hereinafter termed "Inventors", have invented certain new and useful improvements in

**WAFER LEVEL SURFACE PASSIVATION OF STACKABLE INTEGRATED  
CIRCUIT CHIP**

and

[X] have filed a non-provisional application for a United States patent disclosing and identifying the above invention on 19 June 2008 as Application No. 12/142,589; and

[X] have executed an oath or declaration of inventorship for such non-provisional application on:

(1) the 26 day of June, 2008;

(2) the 26 day of June, 2008;

- (3) the 26 day of JUNE, 2008;  
 (4) the 26 day of June, 2008;  
 (5) the 26 day of JUNE, 2008;  
 (6) the 27 day of June, 2008;  
 (7) the 26 day of June, 2008;  
 (8) the 30 day of June, 2008;  
 (9) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (10) the 14 day of July, 2008;  
 (11) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;

(hereinafter termed "application"); and

WHEREAS, Vertical Circuits, Inc., a corporation of Delaware, having a place of business at 10 Victor Square, Scotts Valley, CA 95066 (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial design) on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the applications; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths,

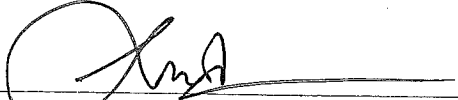
specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said application; (c) for filing and prosecuting substitute, divisional, continuing or additional application covering said invention; (d) for filing and prosecuting application for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any application therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, the Inventors' respective heirs, legal representatives and assigns.

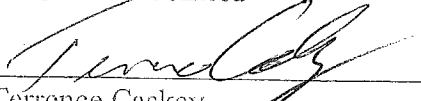
4. Said Inventors hereby warrant and represent that said Inventors have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Inventors hereby authorize any of the following attorneys: Mark A. Haynes, Ernest J. Beffel, Jr., Warren S. Wolfeld, James F. Hann, Bill Kennedy and Kenta Suzue to (a) insert the date of execution of the oath or declaration of inventorship, and (b) insert the application number and filing date of this application when known.

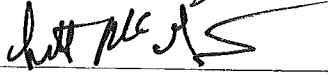
IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the date written below.

  
 \_\_\_\_\_  
 Simon J.S. McElrea

Date: 6/26/08

  
 \_\_\_\_\_  
 Terrence Caskey

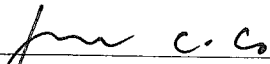
Date: 6/26/08

  
 \_\_\_\_\_  
 Scott McGrath

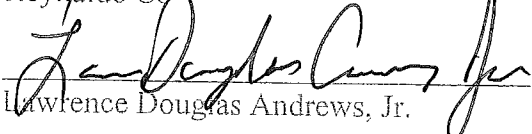
Date: 6-26-08

  
 \_\_\_\_\_  
 DeAnn Eileen Melcher

Date: 06/26/08

  
 \_\_\_\_\_  
 Reynaldo Co

Date: 06/26/08

  
 \_\_\_\_\_  
 Lawrence Douglas Andrews, Jr.

Date: 6-27-2006

W P Pan  
Weiping Pan

Date: 6-26-2008

Grant Villavicencio  
Grant Villavicencio

Date: 6/30/2008

Yong Du  
Yong Du

Date: \_\_\_\_\_

Scott Crane  
Scott Crane

Date: 7/14/08

Zongrong Liu  
Zongrong Liu

Date: \_\_\_\_\_



- (3) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (4) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (5) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (6) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (7) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (8) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (9) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (10) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (11) the 30 day of June, 2008;

(hereinafter termed "application"); and

WHEREAS, Vertical Circuits, Inc., a corporation of Delaware, having a place of business at 10 Victor Square, Scotts Valley, CA 95066 (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial design) on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the applications; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths,

\_\_\_\_\_  
Weiping Pan

Date: \_\_\_\_\_

\_\_\_\_\_  
Grant Villavicencio

Date: \_\_\_\_\_

\_\_\_\_\_  
Yong Du

Date: \_\_\_\_\_

\_\_\_\_\_  
Scott Jay Crane

Date: \_\_\_\_\_

\_\_\_\_\_  
Zongrong Liu

Date: 06/30/2008

*Zongrong Liu*

刘宗荣

**JOINT TO CORPORATE  
ASSIGNMENT**

WHEREAS, the undersigned,

- |   |  |
|---|--|
| (1) Simon J.S. McElrea<br>621 Acorn Court<br>Scotts Valley, CA 95066        | (2) Terrence Caskey<br>236 John Street<br>Santa Cruz, CA 95606                           |
| (3) Scott McGrath<br>13 Terrace View Court<br>Scotts Valley, CA 95066       | (4) DeAnn Eileen Melcher<br>6006 Guadalupe Mines Road<br>San Jose, CA 95120              |
| (5) Reynaldo Co<br>1753 Glenwood Drive<br>Scotts Valley, CA 95066           | (6) Lawrence Douglas Andrews, Jr.<br>22545 Old Santa Cruz Highway<br>Los Gatos, CA 95033 |
| (7) Weiping Pan<br>726 Los Padres Boulevard<br>Santa Clara, CA 95050        | (8) Grant Villavicencio<br>1753 Glenwood Drive<br>Scotts Valley, CA 95066                |
| (9) Yong Du<br>10190 N. Foothill Boulevard<br>Cupertino, CA 95014           | (10) Scott Jay Crane<br>19388 Oak Ridge Drive<br>Aromas, CA 95004                        |
| (11) Zongrong Liu<br>7375 Rollingdell Drive, Unit 72<br>Cupertino, CA 95014 |  |

hereinafter termed "Inventors", have invented certain new and useful improvements in

**WAFER LEVEL SURFACE PASSIVATION OF STACKABLE INTEGRATED  
CIRCUIT CHIP**

and

[X] have filed a non-provisional application for a United States patent disclosing and identifying the above invention on **19 June 2008** as **Application No. 12/142,589**; and

[X] have executed an oath or declaration of inventorship for such non-provisional application on:

(1) the 26 day of June, 2008;

(2) the 26 day of June, 2008;

- (3) the 26 day of JUNE, 2008;  
 (4) the 26 day of June, 2008;  
 (5) the 26 day of June, 2008;  
 (6) the 27 day of June, 2008;  
 (7) the 26 day of June, 2008;  
 (8) the 30 day of June, 2008;  
 (9) the 11 day of July, 2008;  
 (10) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;  
 (11) the \_\_\_\_\_ day of \_\_\_\_\_, 2008;

(hereinafter termed "application"); and

WHEREAS, Vertical Circuits, Inc., a corporation of Delaware, having a place of business at 10 Victor Square, Scotts Valley, CA 95066 (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all rights to apply for foreign patents (including patent, utility model and industrial design) on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the applications; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extension of any of said patents.

2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths,


specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said application; (c) for filing and prosecuting substitute, divisional, continuing or additional application covering said invention; (d) for filing and prosecuting application for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any application therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, the Inventors' respective heirs, legal representatives and assigns.

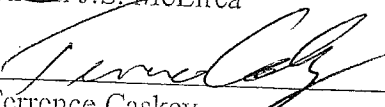
4. Said Inventors hereby warrant and represent that said Inventors have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Inventors hereby authorize any of the following attorneys: Mark A. Haynes, Ernest J. Beffel, Jr., Warren S. Wolfeld, James F. Hann, Bill Kennedy and Kenta Suzue to (a) insert the date of execution of the oath or declaration of inventorship, and (b) insert the application number and filing date of this application when known.

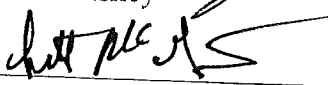
IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the date written below.

  
 \_\_\_\_\_  
 Simon J.S. McElrea

Date: 6/26/08

  
 \_\_\_\_\_  
 Terrence Caskey

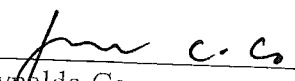
Date: 6/26/08

  
 \_\_\_\_\_  
 Scott McGrath

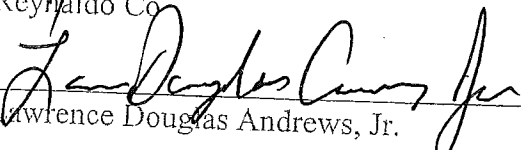
Date: 6-26-08

  
 \_\_\_\_\_  
 DeAnn Eileen Melcher

Date: 06/26/08

  
 \_\_\_\_\_  
 Reynaldo Co

Date: 06/26/08

  
 \_\_\_\_\_  
 Lawrence Douglas Andrews, Jr.

Date: 6-27-2006

W P Pan  
Weiping Pan

Date: 6-26-2008

Grant Villavicencio  
Grant Villavicencio

Date: 6/30/2008

Yong Du  
Yong Du

Date: 7/11/2008

\_\_\_\_\_  
Scott Jay Crane

Date: \_\_\_\_\_

\_\_\_\_\_  
Zongrong Liu

Date: \_\_\_\_\_